



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-27
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDAXLC6-1MY2	8S)Z*6KWSOIB	A	Z6HA	2016-04-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	1.27	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFF	10-0.6-0.5	2	No lead	
Comment	Package: DFN.10.06.055-065-2L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	85J2*6KWSOIB					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.055	mg	supplier	die	Silicon (Si)	7440-21-3		0.052	mg	945455	40945
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	36364	1575
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	18182	787
Leadframe	Copper & its alloys	0.399	mg	supplier	alloy	Copper (Cu)	7440-50-8		0.377	mg	944862	296850
				supplier	alloy	Silicon (Si)	7440-21-3		0.002	mg	5013	1575
				supplier	alloy	Nickel (Ni)	7440-02-0		0.014	mg	35088	11024
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.001	mg	2506	787
				JIG - R	metallization	Nickel (Ni)	7440-02-0		0.005	mg	12531	3937
Die Attach	Other Organic Materials	0.084	mg	supplier	glue or tape	Treated silica	Proprietary		0.007	mg	83333	5512
				supplier	glue or tape	Glycol ethers	Proprietary		0.019	mg	226190	14961
				supplier	glue or tape	Metal Oxide	Proprietary		0.026	mg	309524	20472
				supplier	glue or tape	Curing agent & hardener	Proprietary		0.007	mg	83333	5512
				supplier	glue or tape	Epoxy resin	25068-38-6		0.025	mg	297619	19685
Bonding wire	Other inorganic materials	0.010	mg	supplier	wire	Gold (Au)	7440-57-5		0.010	mg	1000000	7874
Encapsulation	Other Organic Materials	0.722	mg	supplier	mold compound	Silica Fused	60676-86-0		0.676	mg	936288	532283
				supplier	mold compound	Epoxy resin	25068-38-6		0.022	mg	30471	17323
				supplier	mold compound	Phenol resin	29690-82-2		0.022	mg	30471	17323
				supplier	mold compound	Carbon Black	1333-86-4		0.002	mg	2770	1575